

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Pang-Chun Lin	05/27/2010
Chun-Yuan Li	05/27/2010
Fu-Di Tang	05/27/2010
Chien-Ping Huang	05/27/2010
Chun-Chi Ke	05/27/2010
RECEIVING PARTY DATA	
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City:	Taichung
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12859635
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Total Attachments: 1 source=87044_Assignment#page1.tif	

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ASSIGNMENT OF U.S. PATENT APPLICATION

In consideration of the sum of One Dollar in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned

Inventor(s) (1) Pang-Chun LIN (2) Chun-Yuan LI (3) Fu-Di TANG
Full Name(s) (4) Chien-Ping HUANG (5) Chun-Chi KE

Hereby sell, assign and transfer to

Assignee SILICONWARE PRECISION INDUSTRIES CO., LTD.
Name and Address No. 123, Sec. 3, Da Fong Road, Tantzui,
Taichung, Taiwan (R.O.C.)

(hereinafter called the Assignee) the entire right, title, and interest in and to any and all improvements which are disclosed in the Application for United States Letters Patent entitled

Title of Invention: SEMICONDUCTOR PACKAGE HAVING ELECTRICAL CONNECTING STRUCTURES AND FABRICATION METHOD THEREOF

Which application was

Complete either a) executed by the undersigned on _____
b) filed on the _____
Serial No. _____

Including any and all United States Letters Patents which may be granted therefore and any and all extensions, divisions, reissues, substitutes, renewals or continuations thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property.

It is hereby authorized and requested that the Commissioner of Patents issue any and all of said Letters Patent, when granted, to said assignee.

Further, it is agreed that, when requested, without charge to but at the expense of said Assignee, the undersigned will execute all divisional, continuing, substitute, renewal, and reissue patent applications; execute all rightful other papers; and generally do everything possible which said Assignee shall consider desirable for aiding in securing and maintaining proper patent protection.

Date Signed at TAIWAN, R.O.C.
On May 27, 2010

Inventor(s)	<u>Pang Chun Lin</u>	<u>Pang-Chun LIN</u>
Full Signature(s)	<u>Chun Yuan Li</u>	<u>Chun-Yuan LI</u>
	<u>Fu Di Tang</u>	<u>Fu-Di TANG</u>
	<u>Chien-Ping Huang</u>	<u>Chien-Ping HUANG</u>
	<u>Chun Chi Ke</u>	<u>Chun-Chi KE</u>